

## RoHS Compliance Material Declaration Report

|                 |  |                      |  |
|-----------------|--|----------------------|--|
| <b>Company:</b> | Pericom  | <b>Address:</b>      | 3545 North First Street,<br>San Jose,<br>CA, 95134 |
| <b>Name:</b>    | Nang Su  | <b>Phone number:</b> | (408) 435 0800                                     |
| <b>Title:</b>   | Quality Engineer                                     | <b>Date:</b>         | 3/13/2006  |
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| Part Detail         |                                |              |                        |                          |  |
|---------------------|--------------------------------|--------------|------------------------|--------------------------|--|
| Pericom Part Number | Manufacturer part description  | Package Type | Number of Pin/Terminal | Component overall weight |  |
| P17C8154BNAIE       | 64-Bit/66MHz 2-Port PCI Bridge | PBGA         | 304                    | 3.425                    |  |

| RoHS Compliance  |                                  |                                    |
|--|----------------------------------|------------------------------------|
| Is Part compliant to EU RoHS Directive?<br>[1] Yes, [2] Yes with tech exemption*<br>[3] Yes but needs product application exemption*<br>[4] No | RoHS tech exemption [2] details. | Date Component was RoHS Compliant. |
| Yes  | N/A                              | Since Inception                    |

| Content of RoHS restricted materials (g) |         |         |                     |                                |                                      |   |
|--|---------|---------|---------------------|--------------------------------|--------------------------------------|---|
| Lead                                     | Cadmium | Mercury | Hexavalent Chromium | Polybrominated biphenyls (PBB) | Polybrominated Diphenylethers (PBDE) | RoHS restricted substance added intentionally? For what reason? |
| 0  | 0       | 0       | 0                   | 0                              | 0                                    | N/A   |

| Component Soldering Process                                 |                               |   |  |                                     |                          |                             |
|---|-------------------------------|---|--|-------------------------------------|--------------------------|-----------------------------|
| Interconnect Composition, (Metallurgy of the lead/terminal) | JEDEC JEDS97 Pb-free Category | Compatible with a 260C 10s Pb-Free assembly process | Backward compatible with SnPb assembly | Maximum Processing Temperature (°C) | Max Temperature Duration | Max Number of reflow cycles |
| Sn/Ag/Cu  | e1                            | No  | Yes                                    | 250                                 | 40                       | 3                           |

| Plastics (if applicable) |  |                 |                                |
|--------------------------|--|-----------------|--------------------------------|
| Oxygen Index             | Type of plastic material used in the component | Fire: UL Rating | MSL Level (per JEDEC STD 020C) |
| >28%                     | Epoxy Resin                                    | V-0             | 3                              |

| Tin (Sn) Plating (If Applicable)                  |                            |   |                          |   |                              |
|---|----------------------------|---|--------------------------|---|------------------------------|
| Tin (Sn) Plating – is it Matte (M) or Bright (B)? | Tin (Sn) Plating Thickness | Tin (Sn) plating is there a Nickel (Ni) Barrier? - Yes / No | Nickel Barrier Thickness | If no Nickel barrier is the tin (Sn) termination finish heat treated? | Performed Tin Whisker Test ? |
| N/A   | N/A                        | N/A   | N/A                      | N/A   | N/A                          |

| Bismuth (Bi)                         |
|--------------------------------------|
| Bismuth (Bi) Content (if applicable) |
| 0                                    |